

REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	2/10/09	V. LY

NOTES:
MATERIALS AND TOLERANCES:


1. MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES, TOPSIDE ONLY. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
2. FINISH: GOLD PER ASTM B-488 TYPE III CODE A 8-40 MICROINCHES OVER NICKEL PER QQ-N-290 100 MICROINCHES MINIMUM.
3. APPLY LPI SOLDERMASK TOP SIDE ONLY. COLOR: GREEN.
4. SILKSCREEN TOP SIDE WITH WHITE NON-CONDUCTIVE INK.
5. HOLES SIZE AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
6. TOLERANCE ON PCB ROUTE IS ± 0.005 ".
7. ALL HOLES TO BE LOCATED WITHIN ± 0.003 " OF CENTER OF PAD OR OTHER TRUE POSITION.
8. PLATED THRU HOLES .001" MINIMUM WALL THICKNESS.
9. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
10. BOARD WARPAGE: < 0.010 " PER LINEAR INCH MAX.
11. FRONT TO BACK REGISTRATION: ± 0.003 " MAX.
12. PLATING THICKNESS $.002 \pm 0.0005$ FOR METAL-01 AND METAL-04.
13. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
14. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPERATION.
15. MANUFACTURE PER IPC-600 CLASS 2

SPECIAL REQUIREMENTS:

16. CRITICAL LINE WIDTH OF $.018$ " $\pm .001$ " ON METAL-01.
17. EDGE PLATING MUST CONNECT ALL 4 METAL LAYERS.
18. ALL .010 VIAS TO BE FILLED WITH NON-CONDUCTIVE VIA FILL AND OVERPLATED WITH CU BOTH SIDES.

SIZE	QTY	SYM	PLATED	TOL
10	33	+	YES	FILLED
14	110	X	YES	± 3
78	4	◇	YES	± 3

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:		DWN BY:		 HITTITE MICROWAVE CORPORATION 20 Alpha Road Chelmsford, MA 01824	
DIMENSIONS ARE IN INCHES (MM)		V. LY 02/09/09			
DRAWING PRACTICES PER MIL-STD-100		ENGINEER:		TITLE PCB, EVAL HMC5099LC3B	
TOLERANCES:		X. JIANG 02/10/09			
.XX +/- 0.010					
.XXX +/- 0.005					
.XXXX +/- 0.002				SIZE	
ANGLES +/- .5 DEG				CODE ID NO.	
				DRAWING NO.	
				125040	
				REV	
				1	
				SCALE: NONE	
				WT	
				SHEET 1 of 1	